



[10191/3935]

TFW 1763

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s) : LAERMER ET AL.
Filed : January 05, 2005
Serial No. : 10/506,457
For : DEVICE AND METHOD FOR ANISOTROPIC
PLASMA ETCHING OF A SUBSTRATE,
A SILICON BODY IN PARTICULAR
Examiner : Allan W. Olsen
Art Unit : 1763
Confirmation No. : 9990

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

Date: August 15, 2006
Signature: C. H. Li

TRANSMITTAL

SIR:

Please find a Response transmitted herewith for filing in the above-identified patent application.

Applicants hereby request a two-month extension of time for responding to the Office Action of March 30, 2006. The extended period for response expires on August 30, 2006. Please charge the \$450.00 extension fee and any other fee that may be required to **Deposit Account No. 11-0600**. A duplicate of this Transmittal is enclosed.

Dated:

August 15, 2006

By:

Respectfully submitted,

Gerard A. Messina
Gerard A. Messina

Reg. No. 35,952

KENYON & KENYON LLP

One Broadway

New York, NY 10004

Telephone: (212) 425-7200

Facsimile: (212) 425-5288

CUSTOMER NO. 26646

R.N.
42,194